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The fabrication technology for ordered packings from monodisperse silica nanospheres has been developed. This allowed new types of materials to be created: 3D superlattices, including the so-called photonic crystals or photonic band-gap materials.

Experiments to fill an interglobular space with semiconductors, superconductors, optically amplified, ferromagnetic and other materials have been carried out via specially devised techniques. Unique three-dimensional nanosystems thus created were found to exhibit quantum-size and other nanoscale effects such as, for example, non-linear interaction between individual nanocluster electron subsystems.

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